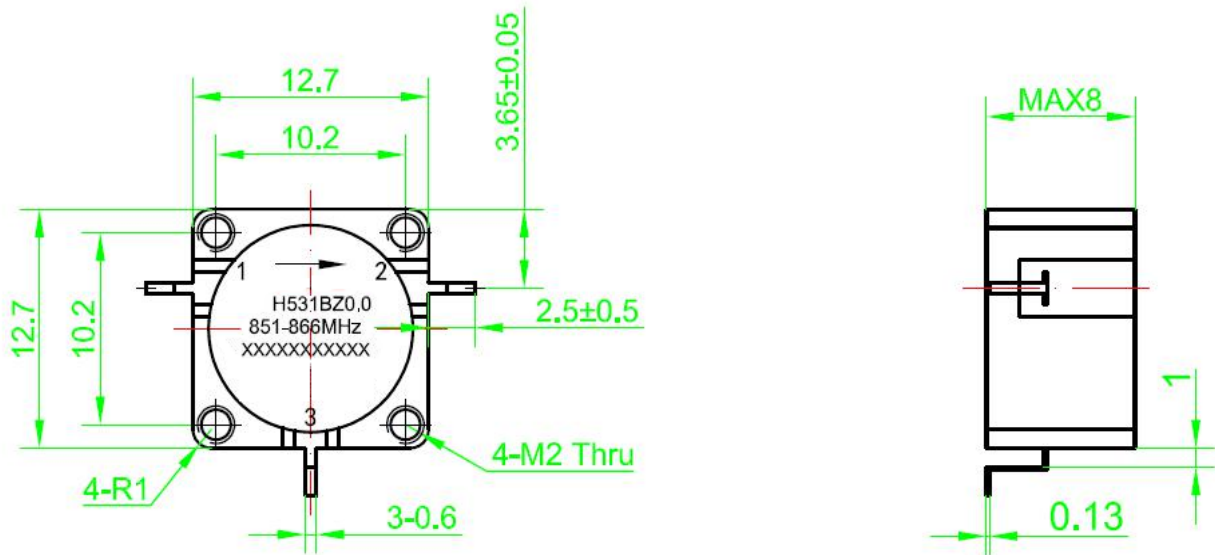


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531B[851-866]MHz	0.851	0.866	0.8585	0.015	21	0.45	1.2	50	
H531B[865-880]MHz	0.865	0.880	0.8725	0.015	21	0.45	1.2	50	
H531B[930-960]MHz	0.930	0.960	0.9450	0.030	21	0.45	1.2	50	
H531B[1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.3	1.15	100	
H531B[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531B[1930-1995]MHz	1.930	1.995	1.963	0.065	23	0.3	1.15	100	
H531B[2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.3	1.15	100	
H531B[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	100	
H531B[2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.3	1.15	100	
H531B[2550-2650]MHz	2.550	2.650	2.600	0.100	23	0.3	1.15	100	